

**Amendment to Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Cancelled)
2. (Currently amended) The thermal management apparatus of Claim 4 12, further comprising a first heat dissipation device coupled to the first electronic component and the thermal conductor, and configured to transfer heat generated by the first electronic component to the thermal conductor.
3. (Original) The thermal management apparatus of Claim 2, wherein the first heat dissipation device is one of a low profile heat sink and heat spreader.
4. (Original) The thermal management apparatus of Claim 2, wherein the carrier substrate is at least part compliant with a standard and the aggregate thickness of the component and the first heat dissipation device is within a dimension requirement of the standard.
5. (Original) The thermal management apparatus of Claim 4, wherein the standard is PICMG 3.0 ATCA, and the dimension requirement is 4.66mm.
6. (Previously amended) The thermal management apparatus of Claim 4, wherein the first side is covered with a nonconductive material and the aggregate thickness of the nonconductive material, the component, and the first heat dissipation device is less than or equal to 4.66 mm.
7. (Currently amended) The thermal management apparatus of Claim 4 12, wherein the thermal conductor is one selected from the group consisting of a solid core conductor, a liquid filled conductor and a heat pipe.

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8. (Cancelled)

9. (Currently amended) The thermal management apparatus of Claim 8 12 wherein the second heat dissipation device is configured to transfer heat to a surrounding environment.

10. (Previously amended) The thermal management apparatus of Claim 9, wherein the second heat dissipation device is one selected from the group consisting of air cooled, liquid cooled, thermoelectric, and phase change.

11. (Currently amended) The thermal management apparatus of Claim 8 12, wherein the second heat dissipation device is removably coupled to the thermal conductor by a fastener and retains the first heat dissipation device against the first electronic component.

12. (Currently amended) A The thermal management apparatus, comprising:  
a carrier substrate having a first side and an opposite second side and an  
opening extending from the first side to the second side;  
a protective cover disposed to substantially enclose the first side; and  
a thermal conductor dimensioned to fit in the opening to facilitate transfer  
of heat generated by a first electronic component attached to the first side for  
dissipation exclusively at the second side; and  
a second heat dissipation device disposed on the second side and  
thermally coupled to the thermal conductor to dissipate said heat transferred away from  
the component disposed on the first side, of Claim 8 wherein the second heat  
dissipation device is configured to thermally couple to a second electronic component disposed on the second side.

13. (Cancelled)

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14. (Currently amended) The modular platform of Claim ~~13~~ 24, further comprising a first heat dissipation device coupled to the first electronic component and the thermal conductor, and configured to transfer heat generated by the first electronic component to the thermal conductor.

15. (Original) The modular platform of Claim 14, wherein the first heat dissipation device is one of a low profile heat sink and heat spreader.

16. (Original) The modular platform of Claim 14, wherein the carrier substrate is at least part compliant with a standard and the aggregate thickness of the component and the first heat dissipation device is within a dimension requirement of the standard.

17. (Original) The modular platform of Claim 16, wherein the standard is PICMG 3.0 ATCA, and the dimension requirement is 4.66mm.

18. (Previously amended) The modular platform of Claim 16, wherein first side is covered with a nonconductive material and the aggregate thickness of the nonconductive material, the component, and the first heat dissipation device is less than or equal to 4.66 mm.

19. (Currently amended) The modular platform of Claim ~~13~~ 24, wherein the thermal conductor is one selected from the group consisting of a solid core conductor, a liquid filled conductor and a heat pipe.

20. (Cancelled)

21. (Currently amended) The modular platform of Claim ~~20~~ 24 wherein the second heat dissipation device is configured to transfer heat to a surrounding environment.

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22. (Previously amended) The modular platform of Claim 21, wherein the second heat dissipation device is one selected from the group consisting of air cooled, liquid cooled, thermoelectric, and phase change.

23. (Currently amended) The modular platform of Claim ~~20~~ 24, wherein the second heat dissipation device is removably coupled to the thermal conductor.

24. (Currently amended) A The modular platform, comprising:

a shelf;

a plurality of modular platform boards, at least one of the boards including a thermal management apparatus, the thermal management apparatus comprising a carrier substrate having a first side and an opposite second side and an opening extending from the first side to the second side;

a protective cover disposed to substantially enclose the first side;

a thermal conductor dimensioned to fit in the opening to facilitate transfer of heat generated by a first electronic component attached to the first side for dissipation exclusively at the second side; and

a second heat dissipation device disposed on the second side and thermally coupled to the thermal conductor to dissipate said heat transferred away from the component disposed on the first side; of Claim 20 wherein the second heat dissipation device is configured to thermally couple to a second electronic component disposed on the second side.

25. (Cancelled)

26. (Currently amended) The method of Claim 25 27, further comprising:

providing a first heat dissipation device coupled to the first electronic component;  
and

coupling the first heat dissipation device to the thermal conductor.

27. (Currently amended) ~~A The method of Claim 25, further comprising:~~

providing a carrier substrate having a first side and an opposite second side and an opening extending from the first side to the second side, and a first electronic component coupled to the first side;

providing a thermal conductor dimensioned to fit in the opening to facilitate transfer of heat generated by a first electronic component attached to the first side for dissipation at the second side;

substantially enclosing the first side with a protective cover; and  
transferring heat from the electronic component exclusively to the second side via the thermal conductor;

disposing a second electronic component on the second side;

providing a second heat dissipation device thermally coupled to the second electronic component;

coupling the second heat dissipation device to the thermal conductor on the second side;

transferring heat from the thermal conductor to the second heat dissipation device; and

transferring heat from the second heat dissipation device to a surrounding environment.

28. (Currently amended) The thermal management apparatus of Claim 4 ~~12~~, further comprising one or more additional openings extending from the first side to the second side, and one or more additional thermal conductors dimensioned to fit in the one or more additional openings to facilitate transfer of heat generated by the first electronic component.

29. (Currently amended) A modular platform of Claim ~~13~~ 24, further comprising one or more additional openings extending from the first side to the second side, and one or more additional thermal conductors dimensioned to fit in the one or more additional openings to facilitate transfer of heat generated by the first electronic component.

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